

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:)
Youzhi E. Xu) Examiner: Not yet assigned
Serial No.: Not yet assigned) Art Unit: Not yet assigned
Filed: Herewith)
For: IMPROVED HEAT TRANSFER THROUGH)
COVALENT BONDING OF THERMAL)
INTERFACE MATERIAL)
Which is a Divisional of Application of:)
Serial No: 10/062,255)
Filed: January 31, 2002)

Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

INFORMATION DISCLOSURE STATEMENT

Sir:

Applicant hereby requests consideration of the enclosed Information Disclosure Statement pursuant to 37 C.F.R §1.97(b). Attached are the PTO Forms 1449 and Forms 892 from the parent application filed on January 31, 2002 (Serial No. 10/062,255). This previous applications are relied upon for an earlier filing date under 35 U.S.C. §120.

Pursuant to C.F.R. §1.98(d), copies of the references are not being provided herewith since they were previously sent to the Patent and Trademark Office.

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Pursuant to 37 C.F.R. § 1.97, the submission of this Information Disclosure Statement is not to be construed as a representation that a search has been made and is not to be construed as an admission that the information cited in this statement is material to patentability.

Respectfully submitted,

BLAKELY, SOKOLOFF, TAYLOR & ZAFMAN LLP

Dated: 2/17, 2004

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Substitute for form 1449B/PTO
**INFORMATION DISCLOSURE
STATEMENT BY APPLICANT**

(use as many sheets as necessary)

Sheet 1 of 1

Complete If Known

Application Number	10/062,255
Filing Date	January 31, 2002
First Named Inventor	Youzhi B. Xu
Group Art Unit	Not yet assigned
Examiner Name	Not yet assigned
Attorney Docket Number	42390P13563

OTHER PRIOR ART - NON PATENT LITERATURE DOCUMENTS

Examiner Initials*	Cite No. 1	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published	T ²
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Examiner
Signature

Wesley Xu

Date
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8/5/03

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Notice of References Cited	Application/Control No.	Applicant(s)/Patent Under Reexamination	
	10/062,255	XU, YOUZHI E.	
	Examiner	Art Unit	Page 1 of 1
	Wesley A. Nicolas	1742	

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*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-2003/0128521	07-2003	Matayabas et al.	361/705
	B	US-2002/0132896	09-2002	Nguyen	524/404
	C	US-5,403,783	04-1995	Nakanishi et al.	438/106
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